



MULTIFUNCTIONAL EM SHIELDED THERMOPLASTIC COMPOSITE

Shielding for EMI/EMC, EMP, and HPM Protection

- Expanded Cu Mesh in-situ integrated into GR/PEEK
 - » Structural capability with no parasitic weight
- Shielding effectiveness equivalent to aluminum
- Applicable to secondary and primary structures
- Thermal energy dissipation



Electronics Box Demonstrator ~ 70% weight reduction

- Exceeded torsion properties of Alu
- Integrated electronics deck

